

ABSTRACT OF THE DISCLOSURE

An epoxy resin composition for semiconductor encapsulation, which comprises the following component (A), component (B), component (C) and component (D):

5 (A) an epoxy resin,

(B) a phenol resin,

(C) a curing accelerator, and

(D) a spherical inorganic filler prepared by surface-treating it with a silane coupling agent having acrylate

10 group or methacrylate group.